onsemi

MOSFET - Power, Single N-Channel, SUPERFET[®], FAST, TOLL-4L 600 V, 125 mΩ, 22 A

NTBL125N60S5H

Description

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application. The TOLL package offers improved thermal performance and excellent switching performance by providing a Kelvin Source configuration and lower parasitic source inductance.

Features

- 650 V @ $T_J = 150^{\circ}C / Typ. R_{DS(on)} = 100 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free / BFR Free and RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

MAXIMUM RATINGS (T_J = 25°C, unless otherwise noted)

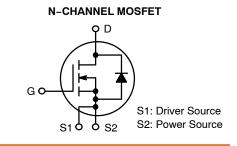
Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V _{DSS}	600	V
Gate-to-Source Voltage	DC	V _{GS}	±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	22	А
	$T_{C} = 100^{\circ}C$		13	
Power Dissipation	$T_{C} = 25^{\circ}C$	PD	152	W
Pulsed Drain Current (Note 1)	T _C = 25°C	I _{DM}	77	А
Pulsed Source Current (Body Diode) (Note 1)		I _{SM}	77	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	–55 to 150	°C
Source Current (Body Diode)		I _S	22	А
Single Pulse Avalanche Energy	l _L = 4.5 A R _G = 25 Ω	E _{AS}	184	mJ
Avalanche Current		I _{AS}	4.5	А
Repetitive Avalanche Energy (Note 1)		E _{AR}	1.52	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			20	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

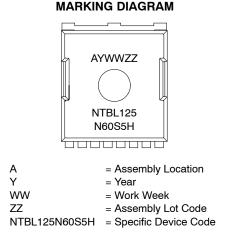
1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. $I_{SD} \leq$ 11 A, di/dt \leq 200 A/µs, V_{DD} \leq 400 V, starting T_J = 25°C.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
600 V	125 m Ω @ V_{GS}= 10 V	22 A







ORDERING INFORMATION

Device	Package	Shipping [†]
NTBL125N60S5H	H-PSOF8L	2000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ ext{ heta}JC}$	0.82	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	43	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

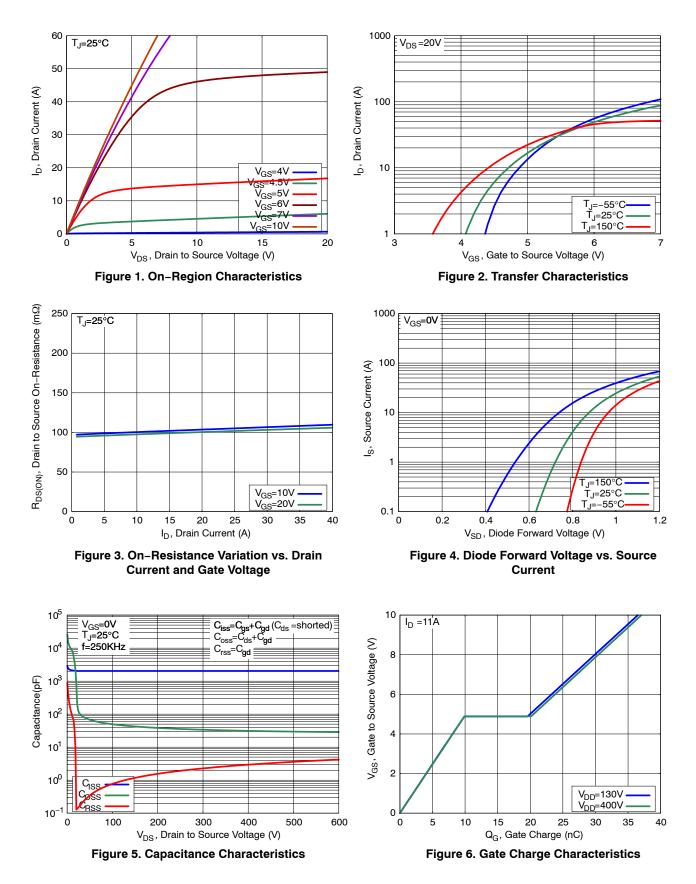
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•				
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 10 mA, T_J = 25°C	600	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	$I_D = 10$ mA, Referenced to 25°C	-	630	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V_{GS} = 0 V, V_{DS} = 600 V, T_{J} = 25°C	-	-	1	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 10 V, I _D = 11 A, T _J = 25°C	-	100	125	mΩ
Gate Threshold Voltage	V _{GS(th)}	V_{GS} = V_{DS} , I_D = 2.1 mA, T_J = 25°C	2.7	-	4.3	V
Forward Trans-conductance	9fs	V _{DS} = 20 V, I _D = 11 A	-	21.7	-	S
CHARGES, CAPACITANCES & GATE	RESISTANCE				-	
Input Capacitance	C _{ISS}	V_{DS} = 400 V, V_{GS} = 0 V, f = 250 kHz	-	2036	-	pF
Output Capacitance	C _{OSS}		-	31.2	-	1
Time Related Output Capacitance	C _{OSS(tr.)}	I_{D} = Constant, V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	485	-	
Energy Related Output Capacitance	C _{OSS(er.)}	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	52.2	-	
Total Gate Charge	Q _{G(tot)}	V _{DD} = 400 V, I _D = 11 A, V _{GS} = 10 V	-	37.1	-	nC
Gate-to-Source Charge	Q _{GS}		-	9.92	-	7
Gate-to-Drain Charge	Q _{GD}		-	10.2	-	
Gate Resistance	R _G	f = 1 MHz	-	1.08	-	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	18.5	-	ns
Rise Time	t _r	l _D = 11 A, R _G = 7.5 Ω	-	5.15	-	
Turn-Off Delay Time	t _{d(OFF)}]	-	56.4	-	1
Fall Time	t _f	1	-	2.7	-]
SOURCE-TO-DRAIN DIODE CHARA	CTERISTICS					
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _{SD} = 11 A, T _J = 25°C	-	-	1.2	V

Forward Diode Voltage	V _{SD}	V_{GS} = 0 V, I_{SD} = 11 A, T_{J} = 25°C	-	-	1.2	V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 V, I_{SD} = 11 A,$	-	336	-	ns
Reverse Recovery Charge	Q _{RR}	dI/dt = 100 A/µs, V _{DD} = 400 V	-	4513	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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TYPICAL CHARACTERISTICS



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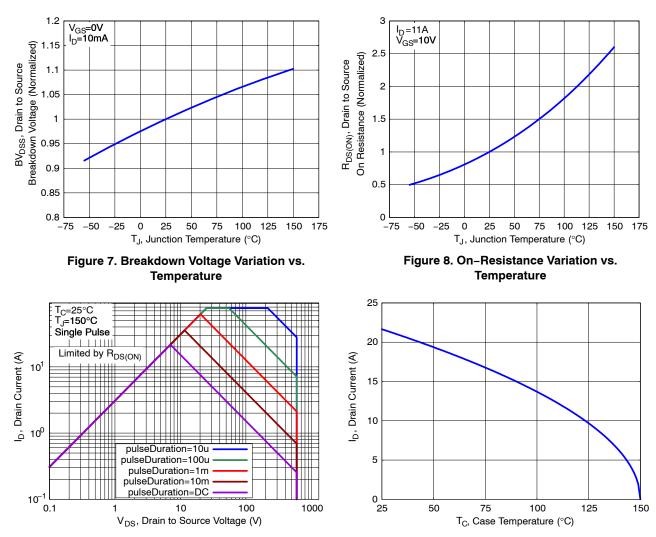


Figure 9. Maximum Safe Operating Area

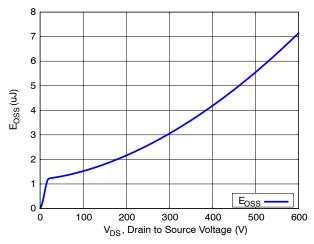


Figure 11. Eoss vs. Drain-to-Source Voltage

Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS

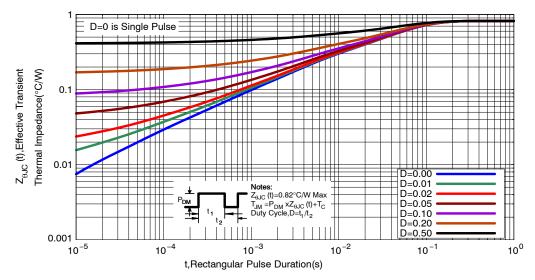
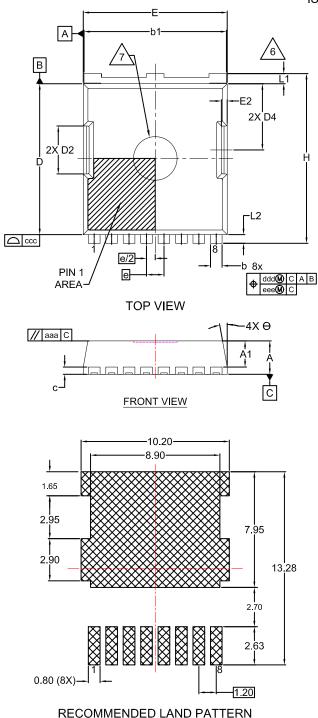
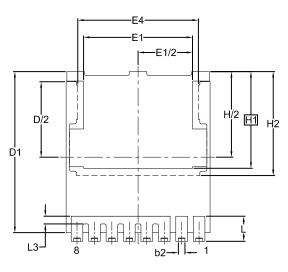


Figure 12. Transient Thermal Impedance

PACKAGE DIMENSIONS

H-PSOF8L 9.90x11.68, 1.20P CASE 100DC ISSUE O





BOTTOM VIEW NOTES:

1. DIMENSIONING AND TOLERANCING PER

3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

ASME Y14.5M, 2009. 2. CONTROLLING DIMENSION: MILLEMETERS.

MIN. NOM. MAX. 2.20 2.40 2.30 А A1 1.70 1 80 1.90 b 0.70 0.80 0.90 b1 9.70 9.80 9.90 b2 0.35 0.45 0.55 с 0.40 0.50 0.60 D 10.28 10.38 10.48 D1 10.98 11.08 11.18 D2 3.20 3.30 3.40 D/2 5.09 5.19 5.29 D4 4.45 4.55 4.65 Е 9.80 9.90 10.00 E1 7.40 7.50 7.60 E2 0.30 0.40 0.50 E4 8.20 8.30 8.40 .20 BSC е н 11.58 11.68 11.78 H1 6.66 BSC H2 7.05 7.15 7.25 H/2 5.79 5.89 5.99 1.63 1.73 1.83 L L1 0.60 0.70 0.80 L2 0.50 0.60 0.70 0.43 L3 0.53 0.63 10° REF θ aaa 0.20 0.20 ccc 0.25 ddd eee 0.20

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